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APPLICATION NO).	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/057,906		01/29/2002	Chih-Jung Ni	MR3029-11	3703
4586	7590	02/24/2005		EXAMINER	
	•	LEIN & LEE	EL ARINI, ZEINAB .		
3458 ELLICOTT CENTER DRIVE-SUITE 101 ELLICOTT CITY, MD 21043			OHE 101	ART UNIT	PAPER NUMBER
				1746	
				DATE MAILED: 02/24/2009	5

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	
Office Action Summan	10/057,906	NI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Zeinab E. EL-Arini	1746	
The MAILING DATE of this communication Period for Reply	appears on the cover sheet with	the correspondence address	
A SHORTENED STATUTORY PERIOD FOR RETHE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CF after SIX (6) MONTHS from the mailing date of this communication - If the period for reply specified above is less than thirty (30) days, and If NO period for reply is specified above, the maximum statutory period for reply within the set or extended period for reply will, by significant to reply within the set or extended period for reply will, by significant the search patent term adjustment. See 37 CFR 1.704(b).	ON. R 1.136(a). In no event, however, may a reply n. a reply within the statutory minimum of thirty (3 priod will apply and will expire SIX (6) MONTH tatute, cause the application to become ABAN	be timely filed 0) days will be considered timely. S from the mailing date of this communication. DONED (35 U.S.C. § 133).	
Status			
Responsive to communication(s) filed on 0 2a) This action is FINAL . 2b)	This action is non-final. owance except for formal matters	•	
Disposition of Claims			
4) Claim(s) 26-27, 29, 31, 33-38, and 40-50 is 4a) Of the above claim(s) is/are with 5) Claim(s) is/are allowed. 6) Claim(s) 26-27, 29, 31, 33-38, and 40-50 is 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and Application Papers 9) The specification is objected to by the Example 10) The drawing(s) filed on is/are: a) Applicant may not request that any objection to Replacement drawing sheet(s) including the contents.	drawn from consideration. s/are rejected. nd/or election requirement. niner. accepted or b) objected to by the drawing(s) be held in abeyance	See 37 CFR 1.85(a).	
11)☐ The oath or declaration is objected to by the		•	
Priority under 35 U.S.C. § 119 12) Acknowledgment is made of a claim for fore a) All b) Some * c) None of: 1. Certified copies of the priority document of the priority d	nents have been received. Itents have been received in Apportionity documents have been received in PCT Rule 17.2(a)).	lication No ceived in this National Stage	
Attachment(s)			
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB, Paper No(s)/Mail Date		mary (PTO-413) ail Date mal Patent Application (PTO-152)	

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 12/08/04 has been entered.

Claims 26-27, 29, 31, 33-38, and 40-50 are pending.

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C.
 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

2. Claims 26-27, 29, 31, 33-38, and 40-50 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

In claim 26, line 9, " at least about" is indefinite term.

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In claim 37, line 2, "further comprising" is indefinite and confusing term.

In claims 43, 47, line 1, "wherein further" is indefinite and confusing term.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 26, 33-37, and 40-50 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's disclosure in combination with Torek et al. (6,562,726 or 6,453,914).

Applicant admitted that the conventional method includes all limitations with the exception of the inert gas.

Torek et al ('726 or '914) teach a method for cleaning a wafer comprising using a cleaning solution, and then rinsing, and the rinsing bath may be agitated by introduction of a gas such as nitrogen, and drying the substrate.

It would have been obvious for one skilled in the art to use the gas to agitate the rinsing solution to improve the conventional cleaning process.

Applicant's disclosure in combination with Torek et al. do not teach the steps of placing the wafer over said stripping solution at least about 100 seconds so as to render said stripping solution left on said wafer dripping, and placing the wafer over a first organic solvent at least 50 seconds so as to render said stripping solution and said first organic solvent left on said wafer dripping down as claimed.

It is well known in the art to withdraw the wafer slowly from the cleaning solution to improve the cleaning process, by dripping most of the cleaning solution before transferring the wafer to a second cleaning or drying solution. One skill in the art would adjust the time to remove the wafer from the stripping solution, and the second cleaning solution, so as to drip most of the stripping solution and organic solution, to obtain optimum results. This is because the time taken for removing the wafer slowly from the cleaning solutions is functionally equivalent to the time taken to place the wafer over the stripping solutions.

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Claims 26-27, 29, 31, 33-38, and 40-50 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lee in combination with Torek et al.

Lee teaches a method for removing polymer residues from a surface of a substrate comprising immersing the wafer in a stripping solution, the stripping solution comprises a hydroxylamine compound, an alcohol amine compound, an anti-corrosion agent, dihydroxybenzene, and water for a time and temperature sufficient to remove the polymeric residues from the surface of substrate. The reference teaches rinsing the substrate with organic solvent, followed by deionized water rinse, and the drying the substrate. See the abstract, col. 1, line 61- col. 2, line 59, col. 3, lines 23-51, col. 5, line 13- col. 6, line 5, examples 2 and 10, and the document in general.

Lee does not teach the time, providing gas to rinsing solution, and the second solvent as claimed.

Torek et al. as discussed supra teach using a gas such as nitrogen to agitate the rinsing solution. See col. 3, line 56- col. 4, line 57, and claims 1, 16-19, 28, 30-38, and the document in general.

It would have been obvious for one skilled in the art to use the gas taught by Torek et al. in the Lee's process to enhance the rinsing process and to enhance removing the stripping solution from the substrate. It would have been obvious for one skilled in the art to repeat the rinsing step to enhance the removing of the residues and the stripping and rinsing solution from the surface of the substrate. It would have been obvious for one skilled in the art to adjust the stripping time, the rinsing time to obtain optimum results. This is because the time is determined based on particular material being removed. See Lee, col. 5, lines 49-67.

Lee in combination with Torek et al. teach all limitations with the exception of the placing steps as claimed.

It would have been obvious for one skilled in the art to adjust the time between removing and immersing the substrate in Lee process to allow stripping solution to drip over the stripping solution, and over the solvent as claimed. This is because it is well known in the art to withdraw the wafer slowly from the cleaning solution to improve the cleaning process, by dripping most of the cleaning solution before transferring the wafer to a second cleaning or drying solution. One skill in the art would adjust the time to remove the wafer from the stripping solution, and the second cleaning

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solution, so as to drip most of the stripping solution and organic solution, to obtain optimum results. This is because the time taken for removing the wafer slowly from the cleaning solutions is functionally equivalent to the time taken to place the wafer over the stripping solutions.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Zeinab E. EL-Arini whose telephone number is (571) 272-1301. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Michael Barr can be reached on (571) 272-1414.

The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Zeinab E. EL-Arini Primary Examiner Art Unit 1746

Zeinab Elanini

ZEE 02/22/05